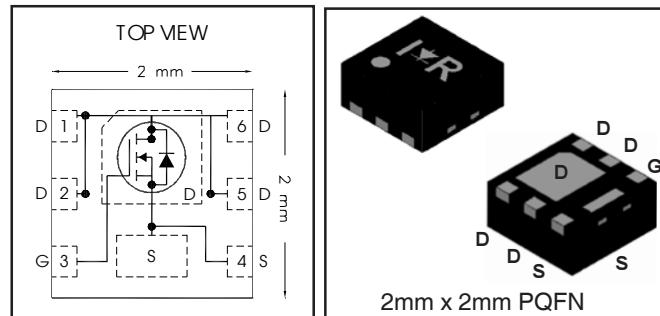


HEXFET® Power MOSFET

<b>V<sub>DS</sub></b>	<b>20</b>	<b>V</b>
<b>V<sub>GS</sub></b>	<b>±12</b>	<b>V</b>
<b>R<sub>DS(on)</sub> max</b> (@V <sub>GS</sub> = 4.5V)	<b>11.7</b>	<b>mΩ</b>
<b>R<sub>DS(on)</sub> max</b> (@V <sub>GS</sub> = 2.5V)	<b>15.5</b>	<b>mΩ</b>
<b>I<sub>D</sub></b> (@T <sub>C(Bottom)</sub> = 25°C)	<b>12①</b>	<b>A</b>



## Applications

- Charge and discharge switch for battery application
- System/Load Switch

## Features and Benefits

### Features

Low R <sub>DS(on)</sub> ( $\leq 11.7\text{m}\Omega$ )
Low Thermal Resistance to PCB ( $\leq 13^\circ\text{C/W}$ )
Low Profile ( $\leq 1.0\text{mm}$ )
Industry-Standard Pinout
Compatible with Existing Surface Mount Techniques
RoHS Compliant Containing no Lead, no Bromide and no Halogen
MSL1, Industrial Qualification

### Resulting Benefits

Lower Conduction Losses
Enable better thermal dissipation
Increased Power Density
Multi-Vendor Compatibility
Easier Manufacturing
Environmentally Friendlier
Increased Reliability

Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRLHS6242TRPbF	PQFN 2mm x 2mm	Tape and Reel	4000	
IRLHS6242TR2PbF	PQFN 2mm x 2mm	Tape and Reel	400	EOL notice # 259

## Absolute Maximum Ratings

	Parameter	Max.	Units
V <sub>DS</sub>	Drain-to-Source Voltage	20	V
V <sub>GS</sub>	Gate-to-Source Voltage	±12	
I <sub>D</sub> @ T <sub>A</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V	10	A
I <sub>D</sub> @ T <sub>A</sub> = 70°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V	8.3	
I <sub>D</sub> @ T <sub>C(Bottom)</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V ②	22②	
I <sub>D</sub> @ T <sub>C(Bottom)</sub> = 70°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V ⑦	18②	
I <sub>D</sub> @ T <sub>C(Bottom)</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V (Package Limited)	12②	
I <sub>DM</sub>	Pulsed Drain Current ①	88	
P <sub>D</sub> @ T <sub>A</sub> = 25°C	Power Dissipation ③	1.98	W
P <sub>D</sub> @ T <sub>C(Bottom)</sub> = 25°C	Power Dissipation ③	9.6	
	Linear Derating Factor ⑤	0.016	W/°C
T <sub>J</sub>	Operating Junction and Storage Temperature Range	-55 to + 150	°C
T <sub>STG</sub>			

Notes ① through ⑦ are on page 2

**Static @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
$BV_{DSS}$	Drain-to-Source Breakdown Voltage	20	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	6.8	—	mV/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	9.4	11.7	$\text{m}\Omega$	$V_{GS} = 4.5\text{V}, I_D = 8.5\text{A}$ ③②
		—	12.4	15.5		$V_{GS} = 2.5\text{V}, I_D = 8.5\text{A}$ ③②
$V_{GS(th)}$	Gate Threshold Voltage	0.5	0.8	1.1	V	$V_{DS} = V_{GS}, I_D = 10\mu\text{A}$
$\Delta V_{GS(th)}$	Gate Threshold Voltage Coefficient	—	-4.2	—	mV/ $^\circ\text{C}$	
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	1.0	$\mu\text{A}$	$V_{DS} = 16\text{V}, V_{GS} = 0\text{V}$
		—	—	150		$V_{DS} = 16\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	100	$\text{nA}$	$V_{GS} = 12\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -12\text{V}$
$g_{fs}$	Forward Transconductance	36	—	—	S	$V_{DS} = 10\text{V}, I_D = 8.5\text{A}$ ②
$Q_g$	Total Gate Charge ⑥	—	14	—	$\text{nC}$	$V_{DS} = 10\text{V}$
$Q_{gs}$	Gate-to-Source Charge ⑥	—	1.5	—		$V_{GS} = 4.5\text{V}$
$Q_{gd}$	Gate-to-Drain Charge ⑥	—	6.3	—		$I_D = 8.5\text{A}$ ② (See Fig.17 & 18)
$R_G$	Gate Resistance	—	2.1	—	$\Omega$	
$t_{d(on)}$	Turn-On Delay Time	—	5.8	—	$\text{ns}$	$V_{DD} = 10\text{V}, V_{GS} = 4.5\text{V}$ ③
$t_r$	Rise Time	—	15	—		$I_D = 8.5\text{A}$ ②
$t_{d(off)}$	Turn-Off Delay Time	—	19	—		$R_G = 1.8\Omega$
$t_f$	Fall Time	—	13	—		See Fig.15
$C_{iss}$	Input Capacitance	—	1110	—	$\text{pF}$	$V_{GS} = 0\text{V}$
$C_{oss}$	Output Capacitance	—	260	—		$V_{DS} = 10\text{V}$
$C_{rss}$	Reverse Transfer Capacitance	—	180	—		$f = 1.0\text{MHz}$

**Diode Characteristics**

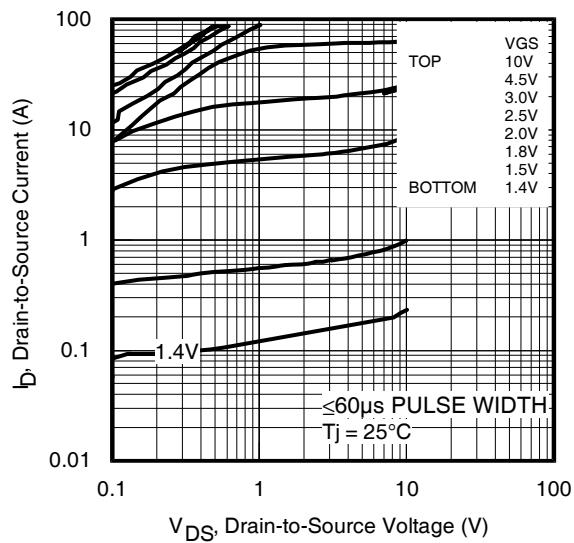
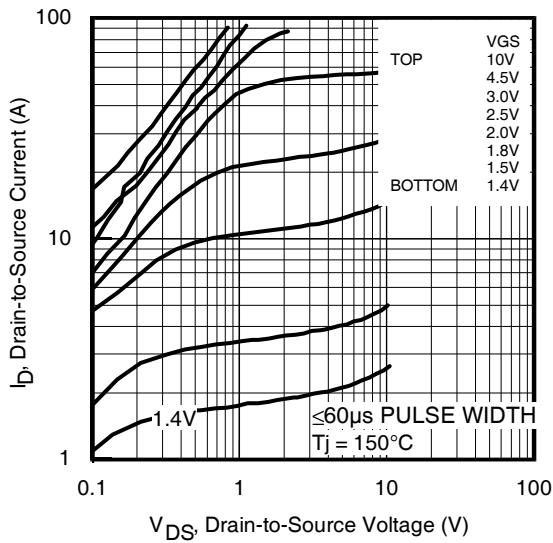
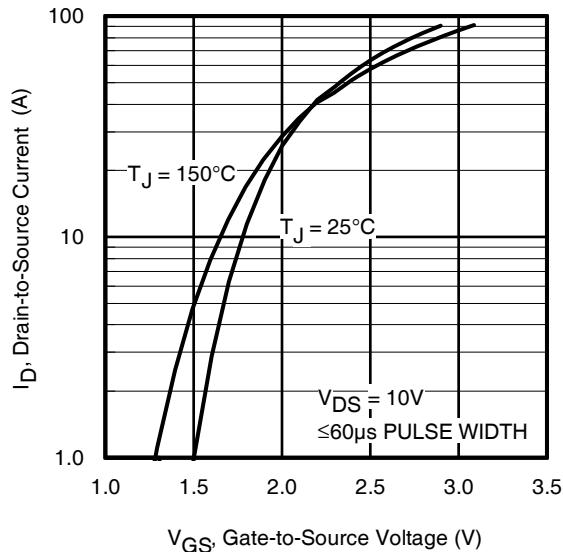
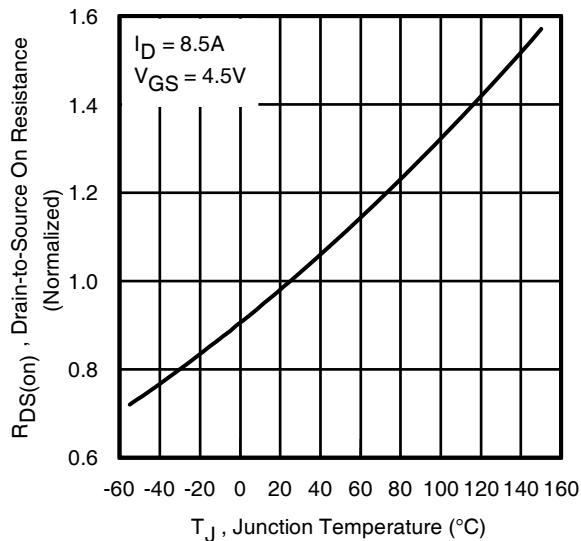
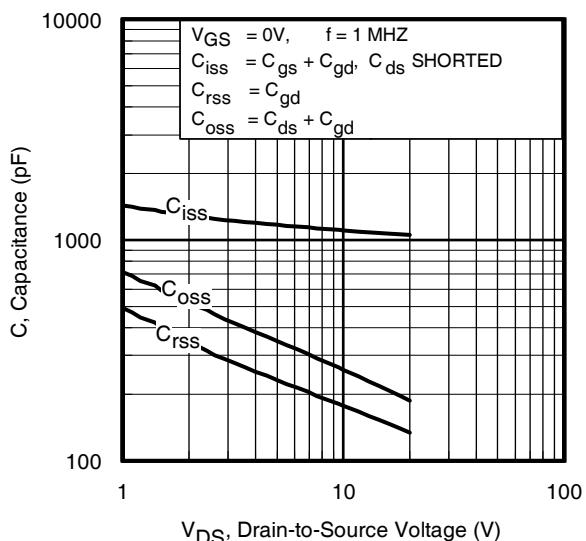
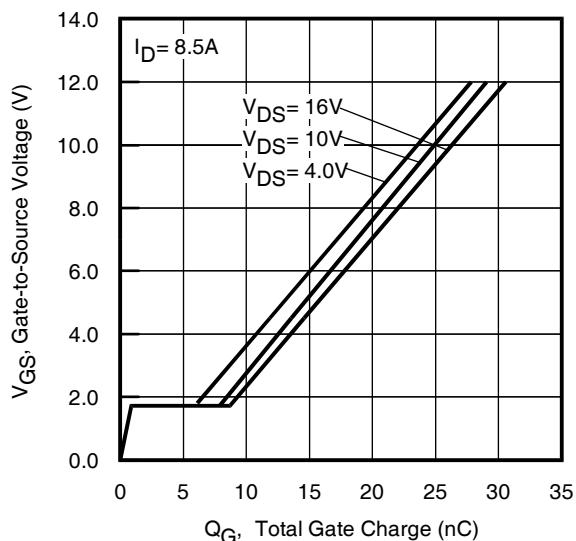
	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	22	A	MOSFET symbol showing the integral reverse p-n junction diode.
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	88		
$V_{SD}$	Diode Forward Voltage	—	—	1.2	V	$T_J = 25^\circ\text{C}, I_S = 8.5\text{A}$ ②, $V_{GS} = 0\text{V}$ ③
$t_{rr}$	Reverse Recovery Time	—	15	23	ns	$T_J = 25^\circ\text{C}, I_F = 8.5\text{A}$ ②, $V_{DD} = 10\text{V}$
$Q_{rr}$	Reverse Recovery Charge	—	12	18	nC	$dI/dt = 210\text{A}/\mu\text{s}$ ③
$t_{on}$	Forward Turn-On Time	Time is dominated by parasitic Inductance				

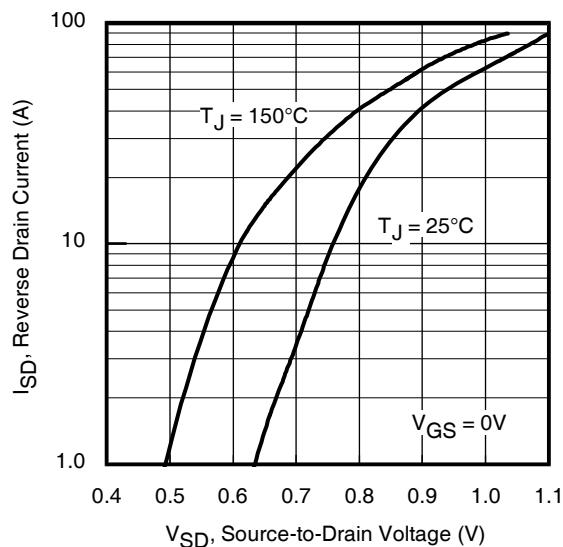
**Thermal Resistance**

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$ (Bottom)	Junction-to-Case ⑤	—	13	$^\circ\text{C/W}$
$R_{\theta JC}$ (Top)	Junction-to-Case ⑤	—	94	
$R_{\theta JA}$	Junction-to-Ambient ④	—	63	
$R_{\theta JA}$ (<10s)	Junction-to-Ambient ④	—	46	

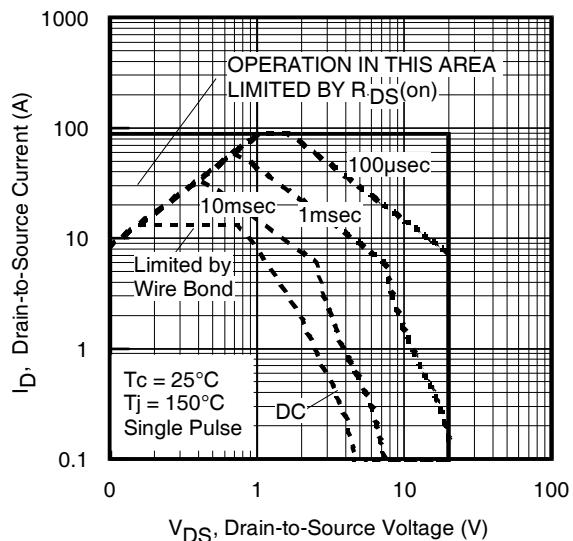
**Notes:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Package is limited to 12A by die-source to lead-frame bonding technology.
- ③ Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ④ When mounted on 1 inch square copper board.
- ⑤  $R_\theta$  is measured at  $T_J$  of approximately  $90^\circ\text{C}$ .
- ⑥ For DESIGN AID ONLY, not subject to production testing.
- ⑦ Calculated continuous current based on maximum allowable junction temperature.

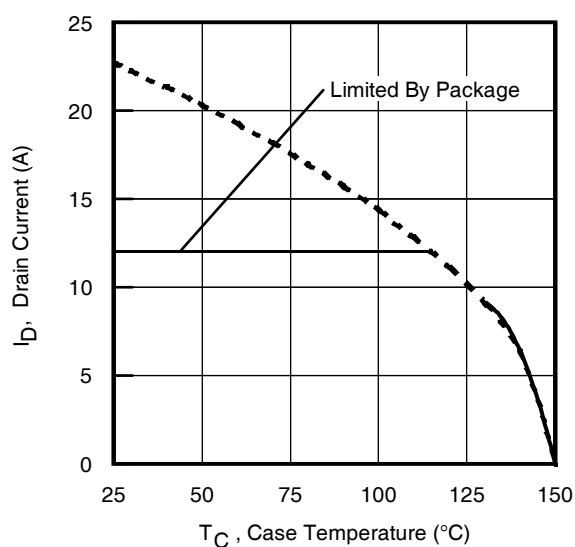
**Fig 1.** Typical Output Characteristics**Fig 2.** Typical Output Characteristics**Fig 3.** Typical Transfer Characteristics**Fig 4.** Normalized On-Resistance vs. Temperature**Fig 5.** Typical Capacitance vs. Drain-to-Source Voltage**Fig 6.** Typical Gate Charge vs. Gate-to-Source Voltage



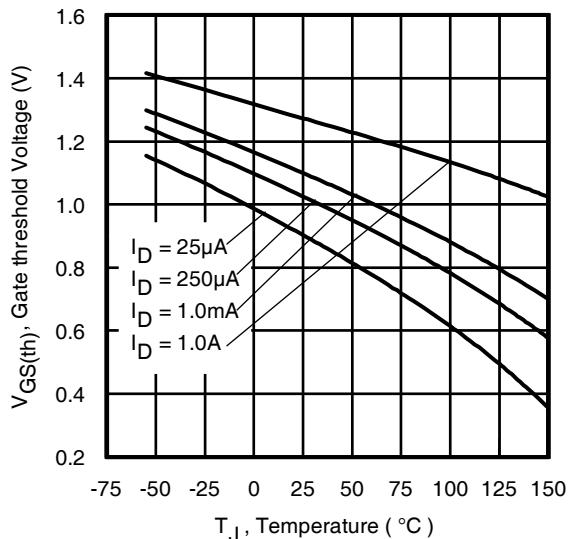
**Fig 7.** Typical Source-Drain Diode Forward Voltage



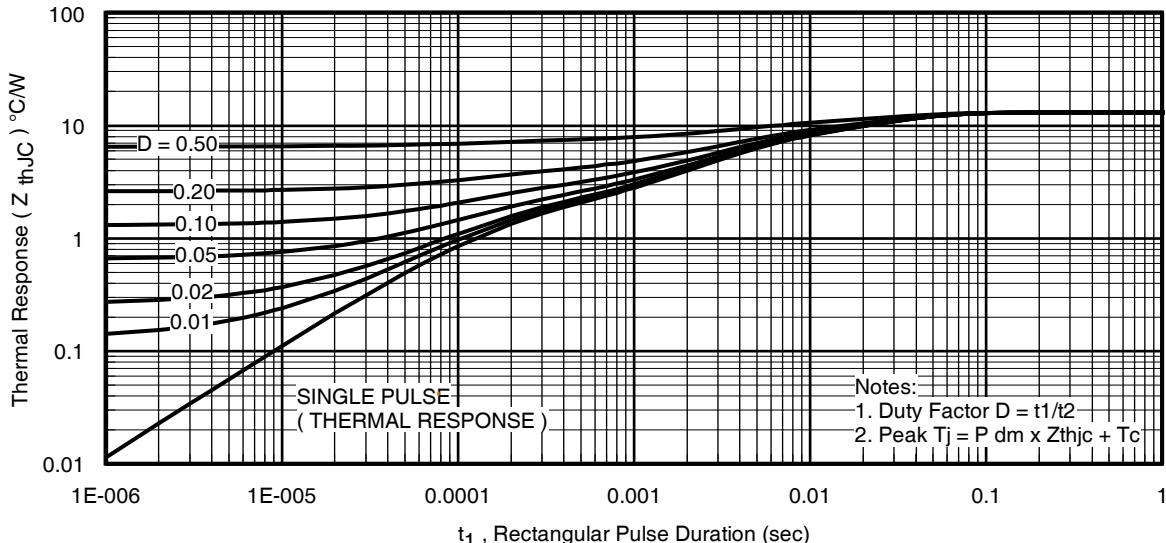
**Fig 8.** Maximum Safe Operating Area



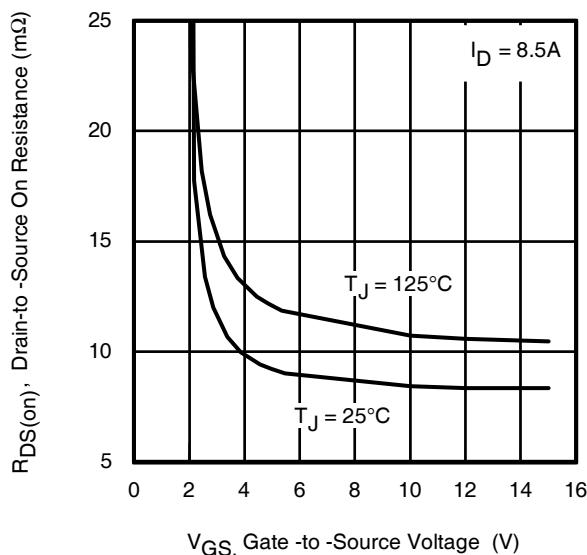
**Fig 9.** Maximum Drain Current vs. Case (Bottom) Temperature



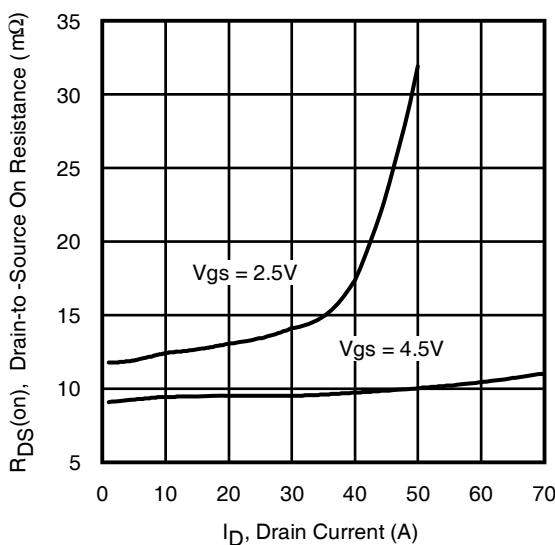
**Fig 10.** Threshold Voltage vs. Temperature



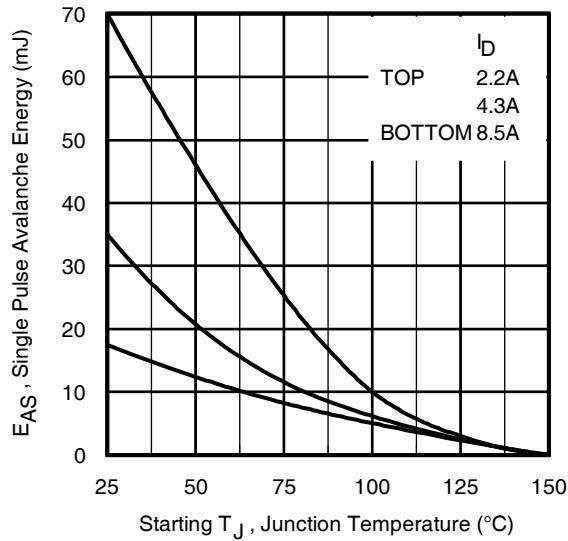
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case (Bottom)



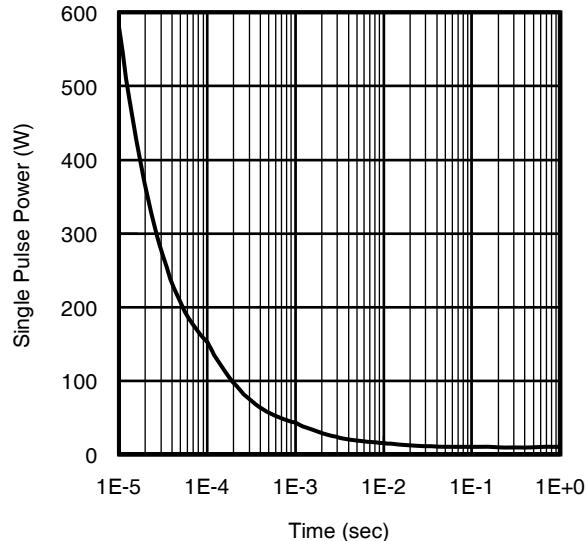
**Fig 12.** On-Resistance vs. Gate Voltage



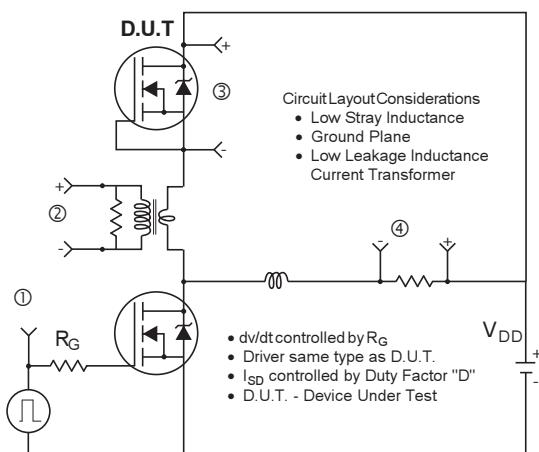
**Fig 13.** Typical On-Resistance vs. Drain Current



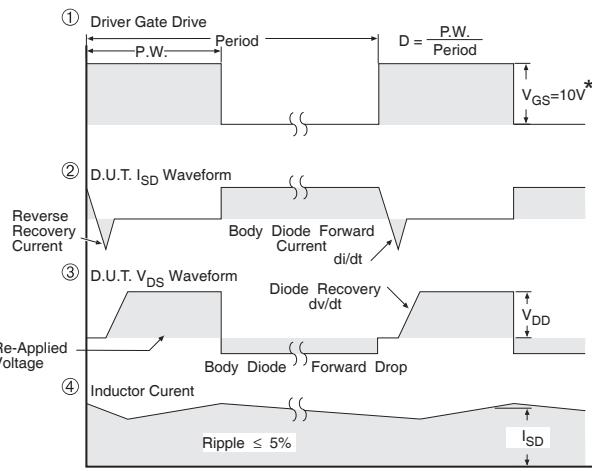
**Fig 14.** Maximum Avalanche Energy vs. Drain Current

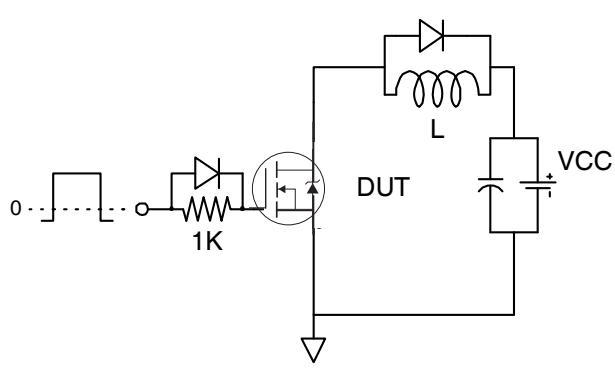
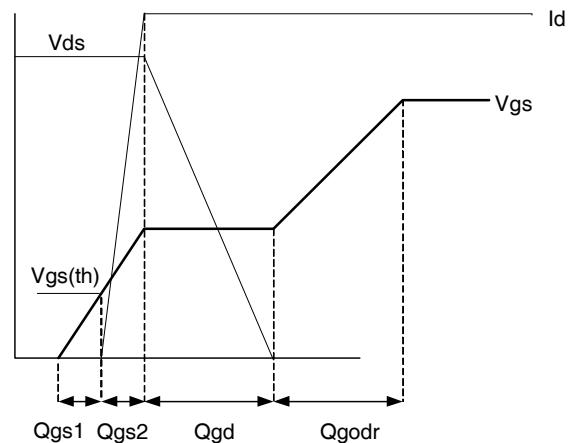
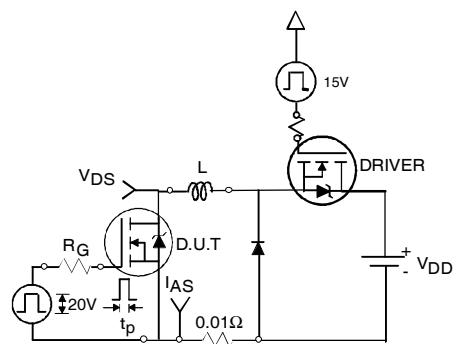
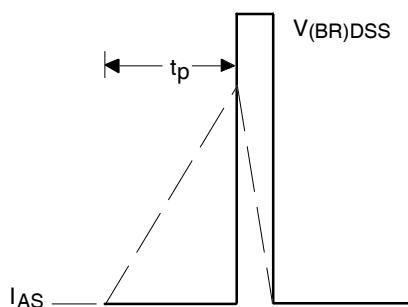
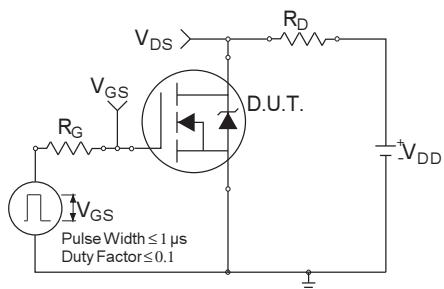
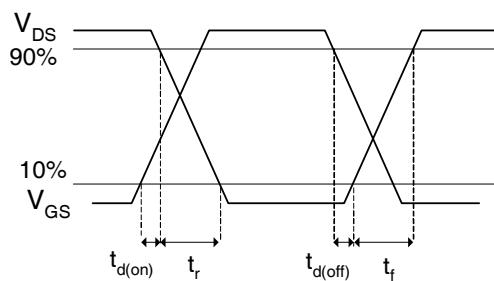


**Fig 15.** Typical Power vs. Time

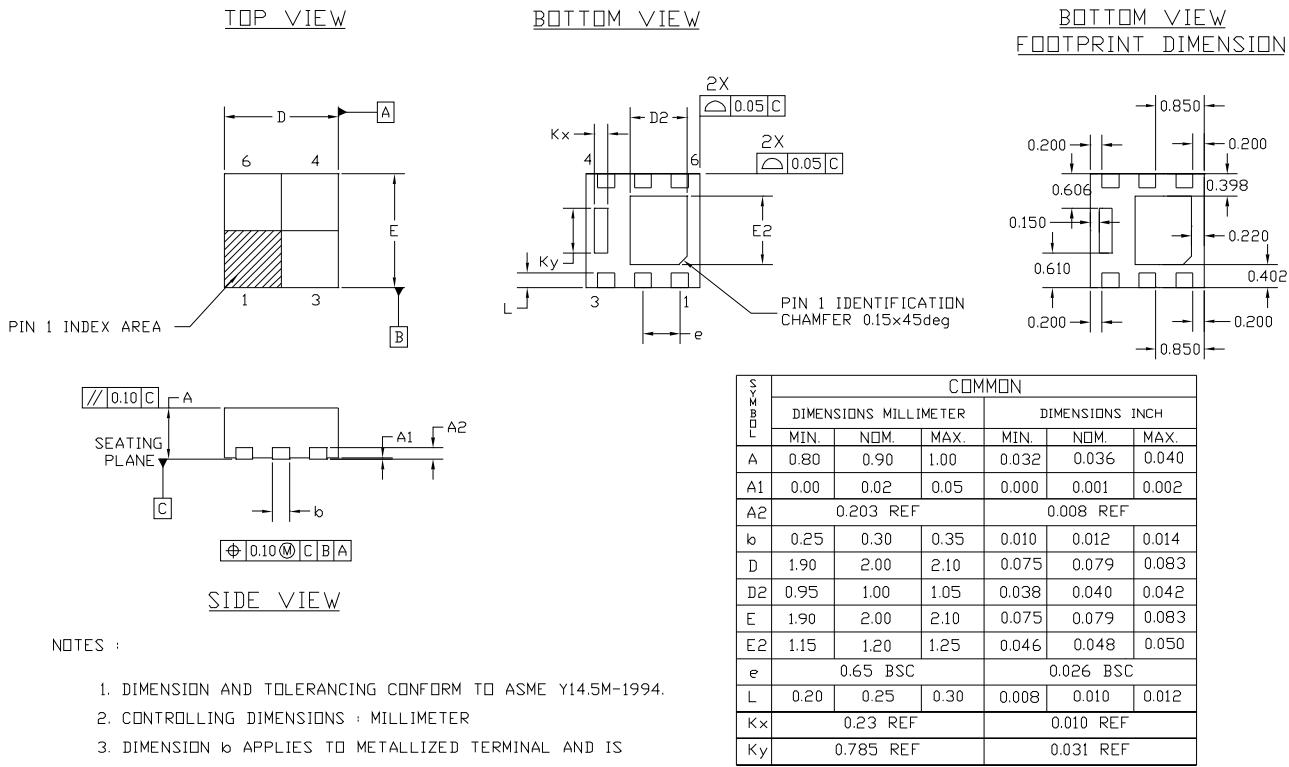


**Fig 16.** Peak Diode Recovery  $dv/dt$  Test Circuit for N-Channel HEXFET® Power MOSFETs



**Fig 17a.** Gate Charge Test Circuit**Fig 17b.** Gate Charge Waveform**Fig 18a.** Unclamped Inductive Test Circuit**Fig 18b.** Unclamped Inductive Waveforms**Fig 19a.** Switching Time Test Circuit**Fig 19b.** Switching Time Waveforms

## PQFN 2x2 Outline Package Details

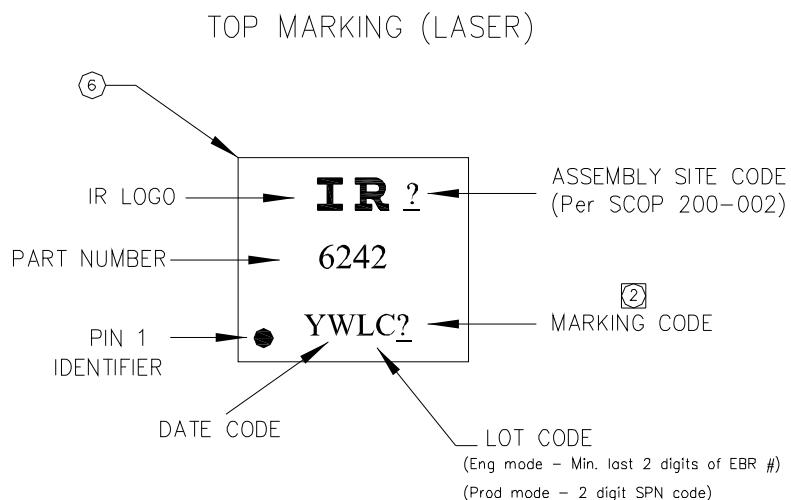


### NOTES :

1. DIMENSION AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
2. CONTROLLING DIMENSIONS : MILLIMETER
3. DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm. FROM TERMINAL TIP.

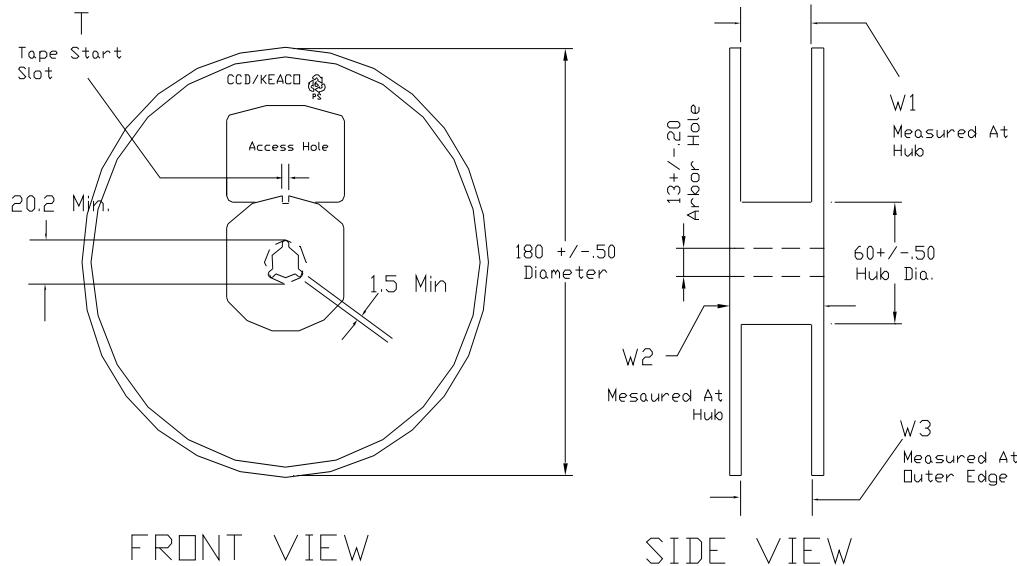
For footprint and stencil design recommendations, please refer to application note AN-1154 at <http://www.irf.com/technical-info/appnotes/an-1154.pdf>

## PQFN 2x2 Outline Part Marking



Note: For the most current drawing please refer to IR website at: <http://www.irf.com/package/>

## PQFN 2x2 Outline Tape and Reel



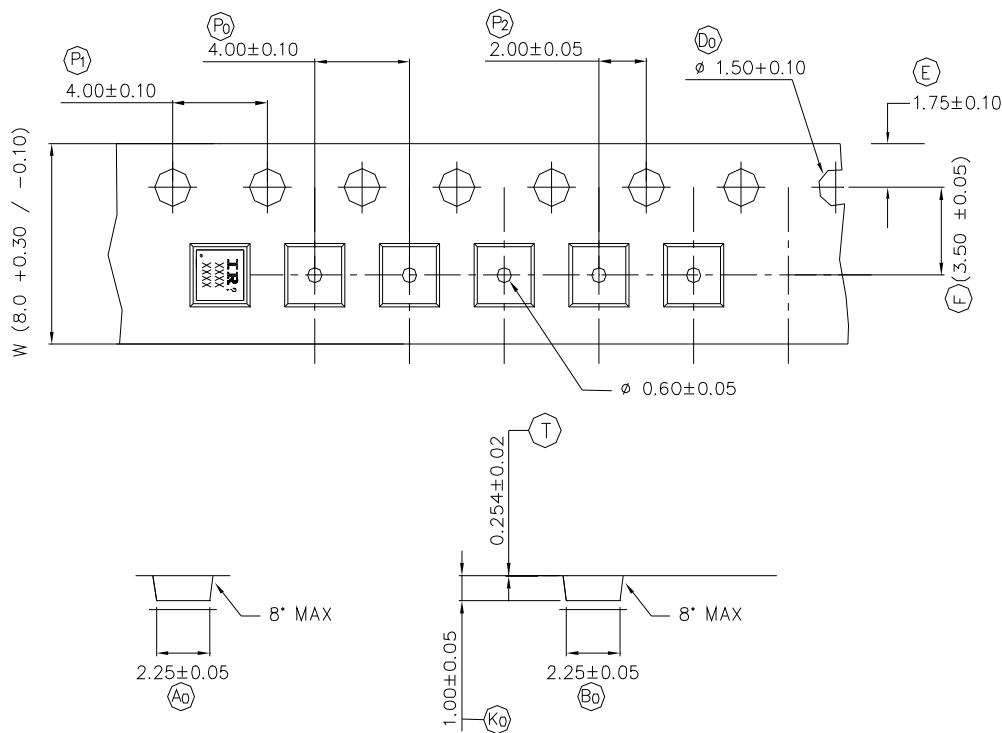
FRONT VIEW

SIDE VIEW

TABLE 1: REEL DETAILS

TAPE WIDTH	T	W1	W2	W3	PART NO
8 MM	$3 \pm 0.50$	$8.4^{+15}_{-0.0}$	14.4 Max	7.90 Min 10.9 Max	91586-1
12 MM	$5 \pm 0.50$	$12.4^{+2.0}_{-0.0}$	18.4 Max	11.9 Min 15.4 Max	91586-2

Note: Surface resistivity is  $\geq 1 \times 10^5$  but  $< 1 \times 10^{12}$  ohm/sq.



NOTE: The Surface Resistivity is  $10^4 - 10^8$  OHM/SQ

**Qualification information<sup>†</sup>**

Qualification level	Industrial <sup>†</sup> (per JEDEC JESD47F <sup>††</sup> guidelines )	
Moisture Sensitivity Level	PQFN 2mm x 2mm	MSL1 (per JEDEC J-STD-020D <sup>††</sup> )
RoHS compliant	Yes	

<sup>†</sup> Qualification standards can be found at International Rectifier's web site

<http://www.irf.com/product-info/reliability>

<sup>††</sup> Applicable version of JEDEC standard at the time of product release.

**Revision History**

Date	Comments
12/17/2013	<ul style="list-style-type: none"><li>• Updated ordering information to reflect the End-Of-life (EOL) of the mini-reel option (EOL notice #259)</li><li>• Updated Qual level from "Consumer" to "Industrial" on page 1, 9</li><li>• Updated data sheet with new IR corporate template</li></ul>

International  
IR Rectifier

**IR WORLD HEADQUARTERS:** 101 N. Sepulveda Blvd., El Segundo, California 90245, USA  
To contact International Rectifier, please visit <http://www.irf.com/whoto-call/>

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